

Certificate of Mailing

Date of Deposit: September 28, 2001

I hereby certify that this paper or fee is being deposited with the United States Postal Service as First Class Mail on the date indicated above and is addressed to the Assistant Commissioner For Patents, Washington, D.C. 20231.

By: Karen M. Forsyth



2815
RECEIVED

SEP-8 2001

TECHNOLOGY CENTER 2000

AMENDMENT TRANSMITTAL LETTER

Attorney Docket No.: D/99580
XER 2 0292

Serial No.: 09/469,122	Filing Date: December 21, 1999	Examiner: C.Chu
Group Art Unit: 2815	Invention: AMORPHOUS SILICON SENSOR WITH MICRO-SPRING INTERCONNECTS FOR ACHIEVING HIGH UNIFORMITY IN INTEGRATED LIGHT-EMITTING SOURCES	

To the Assistant Commissioner of Patents and Trademarks:

Transmitted herewith is an amendment in the above-identified application.
The fee has been calculated as shown below.

CLAIMS AS AMENDED						
	Claims remaining after amendment		Highest Number Previously Paid For	No. of Extra Claims Present	Rate	Additional Rate
Total Claims	26	Minus	26	0	X18	\$.00
Indep. Claims	4	Minus	4	0	X 80	\$.00

- ☒ No additional fee is required.
- ☐ A check in the amount of \$_____ is attached.
- ☐ Charge \$_____ to Deposit Account No. 24-0037.
- ☒ Please charge any additional fees or credit overpayment to Deposit Account No. 24-0037.

Respectfully submitted,

FAY, SHARPE, FAGAN,
MINNICH & MCKEE, LLP

Date: September 28, 2001

Mark S. Svat
Reg. No. 34,261
1100 Superior Avenue
Seventh Floor
Cleveland, Ohio 44114-2518
(216) 861-5582



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF : Lemmi et al.
FOR : AMORPHOUS SILICON SENSOR WITH
MICRO-SPRING INTERCONNECTS FOR
ACHIEVING HIGH UNIFORMITY IN
INTEGRATED LIGHT-EMITTING
SOURCES ✓
SERIAL NO. : 09/469,122 ✓
FILED : December 21, 1999 ✓
LAST OFFICE ACTION : August 8, 2001
EXAMINER : C. Chu
ART UNIT : 2815
ATTORNEY DOCKET NO. : D/99580
XER 2 0292

AMENDMENT A

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

Responsive to the Office Action mailed August 8, 2001, in connection with the above identified patent application, Applicants respectfully request amendment of the application as follows:

IN THE SPECIFICATION

Set forth below is a clean set of all amendments to the specification and the claims. The actual amendments to the specification and the claims are shown in the attachment.

Please substitute the following amended paragraph for the third full paragraph on page 3:

Provided is a hybrid structure or device integrated in a substrate, where in some cases the substrate is substantially transparent to light at infrared wavelengths. Integrated on the substrate are a plurality of micro-spring interconnects, where the micro-spring interconnects are formed of an elastic material that is initially fixed to a surface on the substrate. Upon

R1
Q14